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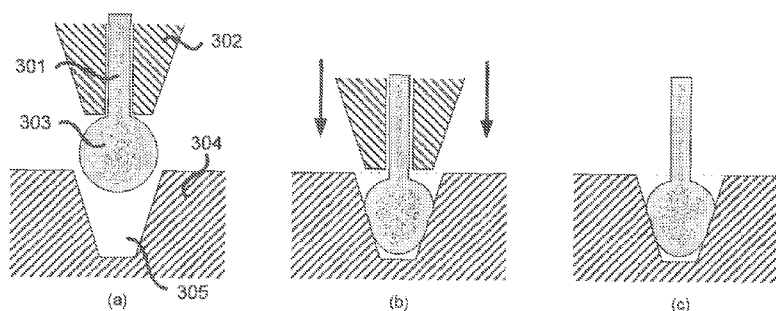
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(54) Title: METHOD FOR THE WAFER-LEVEL INTEGRATION OF SHAPE MEMORY ALLOY WIRES

Figure 2: Squeeze fit of the SMA wire tip.



(57) Abstract: The present invention relates to a method to attach a shape memory alloy wire to a substrate, where the wire is mechanically attached into a 3D structure on the substrate. The present invention also relates to a device comprising a shape memory alloy wire attached to a substrate, where the wire is mechanically attached into a 3D structure on the substrate.